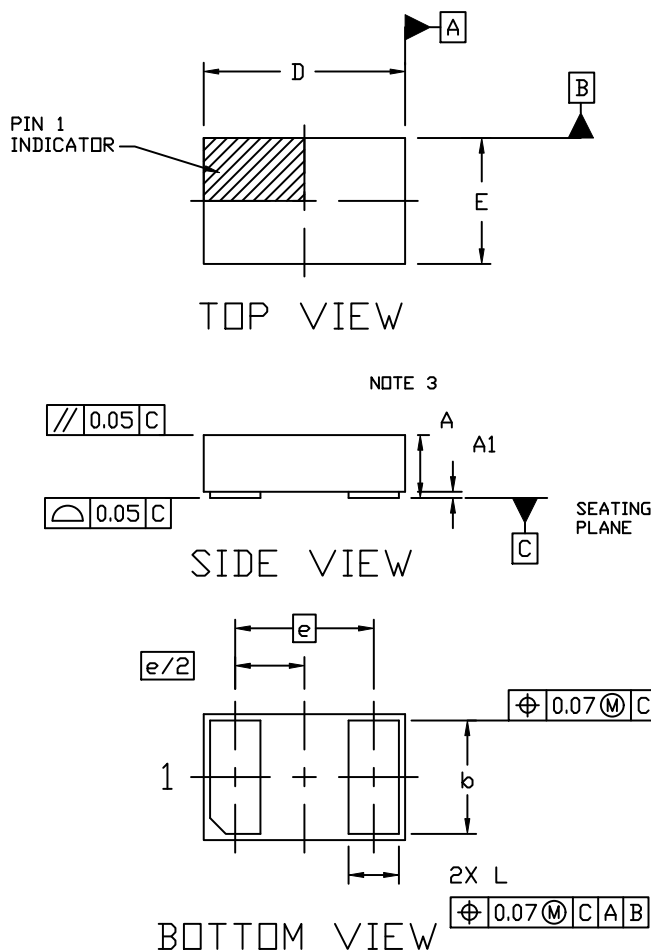




SCALE 4:1

UDFN2 1.6x1.0, 1.1P  
CASE 517CZ  
ISSUE D

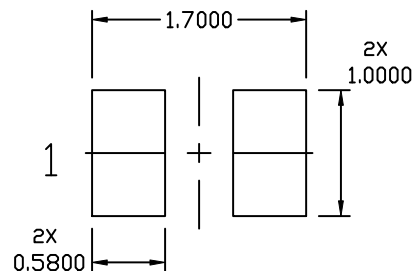
DATE 02 JUL 2020



### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
A1	---	---	0.05
b	0.83	0.88	0.93
D	1.52	1.60	1.68
E	0.92	1.00	1.08
e	1.10 BSC		
L	0.35	0.40	0.45



### RECOMMENDED MOUNTING FOOTPRINT

- \* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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